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# **SPECIFICATION** FOR **LCD MODULE**

# MODULE NO: AFM240128C0-4.8N6NTM **REVISION NO: 00**

Customer's Approval:

	SIGNATURE	DATE
PREPARED BY (RD ENGINEER)		
CHECKED BY		
APPROVED BY		

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DATE	DESCRIPTION
2018-11-30	First release

## **1. DISPLAY CHARACTERISTICS**

Item	Contents	Note
Resolution(H*V)	240×128 Dots	
Colors	Mono TFT display	
Font & Background Color	Font: White, Background: Blue	
Active area (L*W)	110.88 mm(L)×59.13 mm(W)	
Viewing area (L*W)	113 mm(L)×63.64 mm(W)	
Module size (L*W*H)	144 mm(L)×104 mm(W)x14.7(H)	
Back light type	LED	
B/L brightness	500nit	
Touch Panel Type	Without	
Controller IC	UCi6963(FONT-01)	
Viewing Direction	6 o'clock	
Contrast Ratio	500(typ.)	

## 2. Pin Description(CON1):

Pin No.	Symbol	<b>External Connection</b>	Function Description
1	FG		Frame ground
2	VSS	Power Supply	GND
3	VDD	Power Supply	Power supply
4	NC	/	No connection
5	/WR	MPU	Data-write signal for Write Control. LOW: MPU write data into UCi6963.
6	/RD	MPU	Data-read signal for Read Control. LOW: MPU reads data from UCi6963.
7	/CE		Active LOW Chip Select signal
8	C/D		Command/Data Select, or Register select: C/D RD WR Function L L / Data-Read L / L Data-Write H L / Status-Read H / L Command-Write
9	NC	/	No connection
10	/RST	MPU	Active LOW Reset signal
11~18	DB0~DB7	MPU	8-bit bidirectional data bus
19	FS	MPU	Font setting: H=6x8, L=8x8
20	NC	/	No connection
21	NC/LED PWM	NC/MPU	Backlight enable signal, 1=On, 0=Off
22	NC	/	No connection

## 3. Pin Description(CON2):

Pin No.	Symbol	<b>External Connection</b>	Function Description
1	FG		Frame ground
2	VSS	Power Supply	GND
3	VDD	Power Supply	Power supply
4	NC	/	No connection
5	/WR	MPU	Data-write signal for Write Control. LOW: MPU write data into UCi6963.
6	/RD	MPU	Data-read signal for Read Control. LOW: MPU reads data from UCi6963.
7	/CE		Active LOW Chip Select signal
8	C/D		Command/Data Select, or Register select: C/D RD WR Function L L / Data-Read L / L Data-Write H L / Status-Read H / L Command-Write
9	/RST	MPU	Active LOW Reset signal
10~17	DB0~DB7	MPU	8-bit bidirectional data bus
18	FS	MPU	Font setting: H=6x8, L=8x8
19	NC	/	No connection
20	NC/LED PWM	NC/MPU	Backlight enable signal, 1=On, 0=Off
21	NC	/	No connection
22	NC	/	No connection

## 4. Electrical Characteristics

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Operating Temperature Range	Тор	Absolute Max	-20	-	+70	$O_0$
Storage Temperature Range	Tst	Absolute Max	-30	-	+80	0 <sup>0</sup> C
Supply Voltage	VDD		4.5	5.0	5.5	V
Input High Voltage	VIH		0.8*VDD	-	VDD	V
Input Low Voltage	VIL		0	-	0.2*VDD	V
Supply Current	IVCI		-	210	-	mA
Power Consumption	PLCM		-	1050	-	mW

## 5. Controller Information

### 5.1 CONTROL AND DISPLAY INSTRUCTION

### COMMAND TABLE

C/D: 1: Command / 0: Data W/R: 0: Write Cycle / 1: Read Cycle

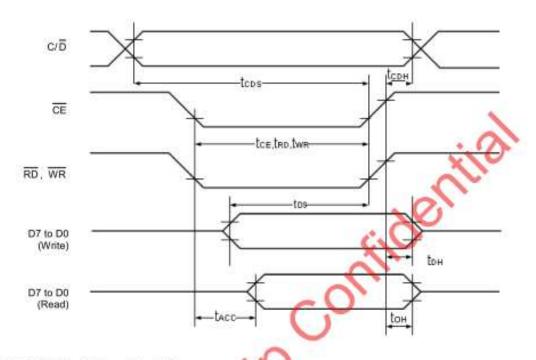
D7-D0: -: Don't Care / #: Valid data

No.	Command	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0	Action	Value
	The Million construction of the	1	0	0	0	1	0	0	0	0	1		21h
1,	Set Cursor Pointer	0	0	#	#	IJ	#	#	#	#	#	Set X address	
- 2		0	0	#	#	#	#	#	#	#	#	Set Y address	-
910	and a second	1	0	0	0	1	0	0	0	1	0		22h
2.	Set Offset Register	0	0	#	#	#	#	#	#	#	#	Data	-
		0	0	0	0	0	0	0	0	0	0		00h
51	Concernence of the second s	1	0	0	0	1	0	0	1	0	0	10 19.000	24h
3,	Set Address Pointer	0	0	#	#	#	#	#	#	#	#	Low address	
_		0	0	#	#	#	#	#	#	#	#	High address	
	Col Toud Upone Adda	1	0	0	1	0	0	0	0	0	0		40h
4.	Set Text Home Addr.	0	0	#	#		#	#	#	#	#	Low address	
_		0	0	#	#	u	#	#	#	#	#	High address	145
5.	Set Text Area	1	0	0	1	0	0	0	0	0	1	Calverage	41h
D.	Set Text Area	0	0	#	#	#	#	#	#	#	#	Columns	-
		0	0	0	0	0	0	0	0	0	0		42h
6.	Set Graphic Home Addr.	1	0	a started to	#	0	and strength	and states in the	#	#	#	Low address	420
0.	Set Graphic Home Addr.	0	0	# #	a la serie de la s	#	#	#	#	and the second s		The second se	-
		1	0	0	#	0	#	#	0	#	#	High address	43h
7.	Set Graphic Area	0	0	#	#	#	#	#	#	#	#	Columns	4311
1	Set Graphic Area	0	0	0	0	0	0	0	0	0	0	Conutins	-
0	OR mode	-	_	1	0	-	0	0	0		0		-
8.	EXOR mode	1	0	+	0	0	0	-	0	0	and the second		-
10.	AND mode	1	0	1	0	0	0	-	0	1	+		-
10.	AND mode	1	0	1	0	0	0	-	1	0	of the Local Division in which the		8xh
11.	Text Attribute mode	0	0	-	U	-	-	-	11		#		- 0.01
12	Internal CG ROM mode	1	0	1	0	0	0	0	-	-	#	S	-
13.	External CG RAM mode	1	0	1	0	0	0	-	-	-	-		
10.	External CO Point mode		0	-		-	10	)	-	-	-	Switch Graphic/Text/Cursor/Blink	1
14.	Display Mode	1	0	1	0	0	1	#	#	#	#	ON/OFF	9xh
15.	Cursor Pattern Select	1	0	1	0	1	0	0	#	#	#	Set cursor: 1~8-line	Axh
16.	Data-write and Increase ADP	1	0	1	1	0	0	0	0	0	0		C0h
10.		0	0	#	1	#	#	#	#	#	#	Data	1
17.	Data-read and Increase ADP	1	1/	1	1	0	0	0	0	0	1		C1h
18.	Data-write and Decrease ADP	1	0	1	1	0	0	0	0	1	0		C2h
		0	0	#	#	#	#	#	#	#	#	Data	
19.	Data-read and Decrease ADP	1.	1	1	1	0	0	0	0	1	1		C3h
20.	Data-write and Non-variable ADP	0	0	1	1	0	0	0	1 #	0	0	Data	C4h
21.	Data-read and Non-variable ADP	1	1		1	1.11	1. PT-	11	1		1	Data	C5h
ALC: NOT THE OWNER OF	Set Data Auto Write	1	0	1	-	1	1	0		0	0		B0h
	Set Data Auto Read	1	0	1	_	1	1	0	_	0	1	<u>(</u>	B1h
	Auto Reset	1	0	1	0	1	1	0	0	1	0	2	B2h
	Screen Peek	1	0	İ	1	1	0	0	0	0	0		E0h
	Screen Copy	1	0	1	1	1	0	1	0	0	0		E8h
	Bit Set/Reset	1	0	1	1	1	1	#	#	#	#	Set/Reset Bit 0~7	Fxh
21.	Dit Gerneset	_		1000	-	-	-			_	0	Joeurreset bit 0*7	_
	2. And March 200 (2010) - 10 - 10 - 2010 (2010) (2010)	11	0	1	1	0	1	0	0	0	-	13	D0h
28.	Whole Screen Reverse	0	0			-			-	-	#	0: Normal 1: Reverse	

No,	Command	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	DO	Action	Value
	2	1	0	0	1	0	1	0	0	0	0	Search concerns and the second	50h
29.	Blink Time (Triple-byte command)	0	0	-	=	1 1	-		#	#	#	000b: 0.066s 100b: 1s 001b: 0.25s 101b: 1.25s 010b: 0.5s 110b: 1.5s 011b: 1.75s 111b: 2s	010b
	1	0	0	-	-	-	I-S	-	-	-	-	(Don't Care)	
30.54	Current Auto Mexicon	1	0	0	1	1	0	0	0	0	0		60h
30.	Cursor Auto Moving (Triple-byte command)	0	0	-	-	-	-		-	-	#	0: disable 1: enable	
	(Thple-byte command)	0	0	-	-	-	-	-	-	-	-	(Don't Care)	10
		1	0	0	1	1	1	0	0	0	0		70h
31.	31. CGROM Font Select (Triple-byte command)	0	0	1	1	1	1	1	1	#	#	00b: Don't care 01b: Don't care 10b: CGROM Font-01 11b: CGROM Font-02	
		0	0	2-0	-		5		-	-	-	(Don't Care)	18

#### 5.2 Interface Timing Diagram and Timing Characteristics

#### MPU Interface Timing



$VDD = +5V \pm 5\%$ ,	GND = 0V, TA = -20-+70°C
4 Merel	

Symbol	Item Test Conditions	Min.	Max.	Unit
tcos	C/D Set up time	100	207	nS
<b>t</b> CDH	C/D Hold time	10	-	nS
tce, tRD, tWR	CE, RD, WR putse width	80	273	nS
tos	Data set up time	80	244	nS
1DH	Data hold time	40	1944 - J	nS
tacc	Access time		150	nS
toH	Output hold time	10	50	nS

## 6. Font Characteristic

LSB MSB	Q	1	2	3	4	5	6	7	8	9	A	В	с	D	E	F
θ		1	11	Ħ	\$	7	8		Ć	3	*	÷	,			
1	Ø	1	2	3	4	5	6	ľ	8	9		1	ć			7
2	8	P	В	C	D	E	F		H	I	J	ĸ	L	T		٥
3	P	G	R	8	T	L	Ļ		28		Z	Ľ	2			
4	*	3	b	C	đ	e	f	ø	h	1	j	k	9	m	n	O
5	p	Q	r	s	t	U	Ų	IJ	X	ы	ž	X	1	3	~	
6	Ç	ü	é	å	ä	å	â	Ģ	ê	e	e	1	î	ì	Ä	Å
7	É		Æ	ô	ö	ò	ú	Ũ.	Q		Ü	¢	£	¥	Pi.	f

## 7. Reliability Test Conditions

No.	Test item	Test condition	Inspection after test
11.1	High temperature storage	80±2°C/120 hours	
11.2	Low temperature storage	-30±2°C/120 hours	
11.3	High temperature operating	70±2°C/120 hours	
11.4	Low temperature operating	-20±2°C/120 hours	
11.5	Temperature cycle	-20±2°C~25°C~70±2°C*10cycles (30min.) (5min.) (30min.)	
11.6	Damp proof test	60°C*90% RH/96 hours	Note 1,2
11.7	Vibration test	Frequency : 10Hz~55Hz~10Hz Amplitude : 1.5mm , X , Y , Z direction for total 3hours (Packing condition)	
11.8	Dropping test	Drop to the ground from 1m height, one time, every side of carton. (Packing condition)	
11.9	ESD test	Voltage : ±800V R : 330Ω C : 150pF Air discharge, 1 time	

Note 2: Conducted after 4 hours of storage at 25°C, 0%RH.

## 8. INSPECTION CRITERION

#### 8.1 Objective

The LCM test criterion are set to formalize LCM quality standards for ODNA with reference to those of the customer for inspection, release and acceptance of finished LCM products in order to guarantee the quality of LCM products required by the customer.

#### 8.2. Scope

The criterion is applicable to all the LCM products manufactured by ODNA.

#### 8.3. Equipment for Inspection

Electrical tester, electrical testing machines, vernier calipers, microscopes, magnifiers, anti-static wrist straps, finger cots, labels, tri-phase cold and hot shock machine, constant temperature and humidity chamber, backlight table, ovens for high-low temperature experiments, refrigerators, constant voltage power supply (DC), desk Lamps, etc.

### 8.4. Sampling Plan and Reference Standards

8.4.1 Sampling plan :

Refer to National Standard GB/T 2828.1---2012/ISO2859-1:1999, level II of normal levels :

#### Major defect: AQL 0.4

#### Minor defect: AQL 1.0

8.4.2 GB/T 2828.1---2012/ISO2859-1:1999 Sampling check procedure in count

8.4.3 GB/T 18910. Standard for LCM parts

8.4.4 GB/T24213-2008 Basic Environmental Test Procedures for Electrical and Electronic Products 8.4.5 IPC-A-610E Acceptability of Electronic Assemblies

0.4.0 IFU-A-0 IUE ACCEPTADIIITY OF ELECTRONIC ASSEMDILES

### 8.5. Inspection Conditions and Inspection Reference

8.5.1 Cosmetic inspection: shall be done normally at 23±5°C of the ambient temperature and 45~75%RH of relative humidity, under the ambient luminance between 500lux~1000lux and at the distance of 30cm apart between the inspector's eyes and the LCD panel and normally in reflected light. For backlight LCM, cosmetic inspection shall be done under the ambient luminance less than 100lux with the backlight on.

8.5.2 The LCM shall be tested at the angle of 45°left and right and 0-45° top and bottom as the following picture showing:



8.5.3 Definition of viewing area(VA)

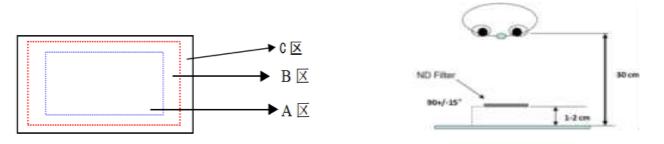
A area : Active area(AA area)

B area : Viewing area(VA area)

C area : Non-viewing area(not viewing after customer assembly)

If there is any appearance viewing defect which do not affect product quality and customer assembly in C area, it's accepted in generally.

The criteria apply to A and B area except chipping and crack.



8.5.4 Inspection with naked eyes(exclusive of the inspection of the physical dimensions of defects carried out with magnifiers)

8.5.5 ND card use method(refer to right conner image) and scope: Multi-bright dot; Mura(Black/Gray pattern uneven); dark line and so on.

8.5.6 Undefined items or other special items, refer to mutual agreement and limited sample. If criterion does not match product specifications/ technical requirement, both should be subject to special inspection criterion agreed by customer.

#### 8.6. Defects and Acceptance Standards

#### 8.6.1 Electrical properties test

8.6.1.1 Test voltage(V) : Refer to the instruction of testers and the product specification or drawing and the display content and parameters and display effects shall conform to the product specification and drawing.

8.6.1.2 Current Consumption(I) : Refer to approved product specifications or drawings.

8.6.1 <u>.3</u> F	unction items	(Defec	t category	/:MA.)	

No.	Defects	Descriptions	Pictures	Inspection method/tools	Defect category
8.6.1.3.1		shows no picture/display in normal connected situation.		Naked eyes/ testers	MA.
8.6.1.3.2	Missing segment	Shows missing lines in normal display		Naked eyes/ testers	MA.
8.6.1.3.3	Dark line	Only visible on gray pattern, 1 or more vertical/horizontal lines:5%ND,not visible,OK	1	Naked eyes/ testers	MA.
8.6.1.3.4	POL angle defect	Not accepted	нт 98 рео L 9(1) рад (1) рад (1) рео L 9(1) рад (1) р	Naked eyes/ testers	MA.
8.6.1.3.5	Image retention (sticking)	Chess pattern stays for 30mins and change to 50% gray pattern,disappear time <10s, OK; if time>10s, NG		Naked eyes/ testers	MA.
8.6.1.3.6	Flicker	Refer to limit sample if essential or flicker value<- 30dB(measured by CA310A); OK		Naked eyes/ CA310A	MA.
8.6.1.3.7	Display abnormal	Not accepted		Naked eyes/ testers	MA.
8.6.1.3.8	Cross-talk	Refer to limited sample	*	Naked eyes/ limited sample	MA.
8.6.1.3.9	Display dim/bright	Refer to limited sample	1	Naked eyes/ limited sample	MA.
8.6.1.3.10	Contrast	Refer to limited sample	1	Naked eyes/ limited sample	MA.
8.6.1.3.11	Huge	Out of spec, not accepted	1	Ammeter	MA.

	current				
8.6.1.3.12	TP function defect	Not accepted	1	Naked eyes/ Touch/ test program	MA.

#### 8.6.2 LCD dot/line defect

8.6.2.1 LCD pixel dot defect(defect category : MI.)

S<5" 1	5"≤S<10"	10"≤S<15"	
1	2		
	2	2	
0	1	1	
0	0	1	
1	2	3	
2	3	4	
1	1	2	
0	0	0	
3	4	5	
ND 3%hidden, OK			
	1 0 3	2         3           1         1           0         0           3         4	

Remark: 2 bright dots distance DS≥15mm 2 dark dots distance DS≥5mm

1) Bright dot: Power on LCM and RGB dot in black display

2) Dark dot: Power on LCM and gray or black dot in RGB display

3) Multi-bright dot: Power on LCM and fluorescent tiny dot in black display(only visible in black display)

#### 8.6.2.2 LCD appearance dot defect (defect category : MI.)

No.	Item		Inspection criterion			Picture	Inspection	
NO.	nem	Si	ze	S<5"	5"≤S<10"	10"≤S<15"	Ficture	method/tools
		D≤0	).15	Not count	Not count	D≤0.2mm		
		0.15<	D≤0.25	3	3	Not count	<b>1</b> <sup>b</sup>	Neked even
		0.25<	D≤0.30	1	2	0.2~0.35mm	· · · ·	Naked eyes /film card
	Dot defect	0.30<	D≤0.35	0	1	Q'ty ≤ 4	r a n	
8.6.2.2.1	(black dot,	0.35<	D≤0.50	0	0	1	D=(a+b)/2	/magnifier
	white dot)	D>	·0.5	0	0	0	D=(a+b)/2	
		Remark :	D≤0.15m	m, not cou	nt.Multi-dot	as bulk is not	accepted.	
		Count do	t quantity≤	≦ 5				
		2 round d	ots or line	ar dots in	1 cm is judo	ged as multi-de	ot.	
		Length	Width	S<5"	5"≤S<10"	10"≤S<15"		
		(mm)	(mm)	0.0	5 20 10	10 20 10		
		Not	W<0.03	Accented	Accepted	Accepted	b=	
	Line	count	W=0.00	7100007100	/10000100	/ locepted		
	defect	L≤5	0.03≤W	3	3	Not count	<u> </u>	Naked eyes
8.6.2.2.2	(visible	L=0	<0.05	0	0		N T	/film card
	when	L≤5	0.05≤W	0	1	3		/magnifier
	power on)	2=0	<0.08			•	1-	
		L≤8	0.05≤W	0	0	1		
		L=0	<0.08	0	,			
		L>8	W>0.08	0			2.7 <b>0</b>	

		Remark :									
		Invisible when powe	isible when power on,only visible in special angle against light, show as								
		watermark/folding/s	cratch but c	an not be to	uched, no co	ntrol or refer	to keeping				
		sample.									
	Polarizer	Size(mm)	S<5"	5"≤S<10"	10"≤S<15"						
	convex-	D≤0.20	Not count	Not count	Not count						
	concave	0.20 <d≤0.5< td=""><td>2</td><td>2</td><td>3</td><td>-</td><td>Naked eyes</td></d≤0.5<>	2	2	3	-	Naked eyes				
8.6.2.2.3	dot defect,	0.50 <d≤0.8< td=""><td>0</td><td>1</td><td>5</td><td></td><td>/film card</td></d≤0.8<>	0	1	5		/film card				
	polarizer	0.8 <d≤1.5< td=""><td>0</td><td>0</td><td>1</td><td>• a •</td><td>/magnifier</td></d≤1.5<>	0	0	1	• a •	/magnifier				
	bubble defect	D>1.5mm	0	0	0						

### 8.6.3 Chipping defect

No.	Item		Accepte	d criterion(mm)		MA.	MI.
	ITO conductive side	Х	/	≤1/8L	1		
0.004		Y	Y≤1/6W	1/6W <y≤1 4w<="" td=""><td>1/4W <y< td=""><td></td><td>I</td></y<></td></y≤1>	1/4W <y< td=""><td></td><td>I</td></y<>		I
8.6.3.1		Accept	2	2	0		V
			1				
	Corner chipping	Х	1	≤1/6L	1		.1
	(ITO pins position)	Y	Y≤1/2W	1/2W <y≤w< td=""><td>W <y< td=""><td></td><td>V</td></y<></td></y≤w<>	W <y< td=""><td></td><td>V</td></y<>		V
8.6.3.2	1	Accept	2	1	0		
		per 6.3.3; black bord	at the same er of the fra	red in sealed edge time it should no ame and the corn ection position per	er chipping		
	Chipping in sealed area (outside chipping)	Х	1	≤1/8L	/		
		Y(outside chipping)	Not enter into	Enter Y≤H	H <y< td=""><td></td><td></td></y<>		
		Y(inside chipping)	sealant	Enter Y≤1/2H	1/2H <y< td=""><td></td><td></td></y<>		
8.6.3.3		Z	≤T	≤1/2T	/		$\checkmark$
	2	Accept	2	1	0		
	Chipping in sealed area (inside chipping)	The standards of inner and outer chipping on edge sealing area are same. When the chipping occurred in the opposite of stage, Y as per the chipping on the non-conduction side standard in 6.3.1					
8.6.3.4	Conductive side	Х	1	≤1/6L	1		$\checkmark$

(back side chipping)	Y	Y≤1/3W	1/3W <y≤2 3w<="" th=""><th>2/3W <y< th=""><th></th><th></th></y<></th></y≤2>	2/3W <y< th=""><th></th><th></th></y<>		
y y	Accept	2	2	0		
	Chipping ir	nto ITO side,	refer to 6.3.1			
	x	/	≤1/8L	/		
cutting and LCD burrs	Y	≤1/6W	1/6W <y≤1 5w<="" td=""><td>1/5W <y< td=""><td></td><td></td></y<></td></y≤1>	1/5W <y< td=""><td></td><td></td></y<>		
	Z	/	/	/		N
	Accept 1 1 1					
	The outside protruding control as per the tolerance of drawing.					
Crack	expand to	Not allow to occur cracks without direction; the crack expand to inside is NG, but to outside is OK (confirmed as per the damaged standard)				
	Protruding LCD poor cutting and LCD burrs	Y     Accept       Accept     Chipping ir       Protruding LCD poor     X       Y     X       Y     Z       Accept     Y       Y     Z       Accept     The outsid of drawing       Crack     Not allow t expand to	YY $\leq 1/3W$ YAccept2Accept2Chipping into ITO side,Y $\leq 1/6W$ Y $\leq 1/6W$ Y $\leq 1/6W$ Z/Accept1The outside protruding of drawing.CrackNot allow to occur crace expand to inside is NG	YY $\leq 1/3W$ $1/3W < Y \leq 2/3W$ Accept22Chipping into ITO side, refer to 6.3.1Protruding LCD poor cutting and LCD burrsX/Y $\leq 1/6W$ $1/6W < Y \leq 1/5W$ Y $\leq 1/6W$ $1/6W < Y \leq 1/5W$ Z//Accept11The outside protruding control as per the soft drawing.Not allow to occur cracks without direction expand to inside is NG, but to outside is C	YY ≤ 1/3W1/3W < Y ≤ 2/3W2/3W < YYAccept220Accept220Chipping into ITO side, refer to 6.3.1X/Protruding LCD poor cutting and LCD burrsX/≤1/8LY≤1/6W1/6W < Y≤1/5W	YY ≤ 1/3W1/3W < Y ≤ 2/3W2/3W < YAccept220Accept220Chipping into ITO side, refer to 6.3.1X/Protruding LCD poor cutting and LCD burrsX/≤ 1/8LY≤ 1/6W1/6W < Y ≤ 1/5W1/5W < YZ//Accept11The outside protruding control as per the tolerance 

Remark :

X means the length of chipping;

Y means the width;

Z means the thickness;

W means the step width of the two glasses;

H means the distance from the glass edge to the sealant inner edge;

T means glass thickness.

#### 8.6.4 Backlight components

	No.	Item	Description	Accepted criterion	MA.	MI.
	8.6.4.1	No backlight wrong Color	/	Rejected		
	8.6.4.2	Color deviation	When powered on, the LCD color differs from its sample and found that the color not conforming to the drawing after testing.	Refer to sample and drawing		
	8.6.4.3	Brightness deviation	When powered on, the LCD brightness differs from its sample and is found after testing not conforming to the drawing; or if it conforms to the drawing but the brightness over ±40% than its typical value.	Refer to sample and drawing		
	8.6.4.4	Uneven brightness	Uneven on the same LCD and out of the specification of the drawing. The no specification evenness= (the max value-the min value)/ mean value< 70%.	Refer to sample and drawing		
	8.6.4.5	Spot/line/ scratch	When power on, it has dirty spot, scratches and so on spot and line defects.	Refer to 6.2.2		$\checkmark$
8.6.5 <u>N</u>	letal frame	(Metal Bezel)				

 No.
 Item
 Description
 Accepted criterion
 MA.
 MI.

8.6.5.1	Material & surface treatment	Metal frame/surface treatment do not conform to the specifications.	Rejected	$\checkmark$	
8.6.5.2	Tab twist Unconformity /Tab not twisted	Wrong twist method or direction and twist tabs are not twisted as required.	Rejected	$\checkmark$	
8.6.5.3	Bezel paint loss	1.Front surface : Paint peel off and scratch to the			$\checkmark$
8.6.5.4	Bezel scratch	bottom Dot:D≤0.5mm, exceeds 3;			$\checkmark$
8.6.5.5	Painting peel off, discoloration, dent, and scratch	Line:L≤3.0mm,W≤0.05mm exceeds 2; 2.Front dent, air bubble and side with paint peeling off scratch to the bottom Dot: D≤1.0mm, exceeds 3; Line:L≤3.0mm,W≤0.05mm, exceeds 2;	Rejected		$\checkmark$
8.6.5.6	Burr	Burr(s) on metal bezel is so long as to get into viewing area.	Rejected		$\checkmark$

### 8.6.6 FPC

No.	ltem	Description	Accepted criterion	MA.	MI.
8.6.6.1	Model &P/N	Material model & P/N	Keep the same with drawing and technical requirement	$\checkmark$	
8.6.6.2	Dimension/ position	Dimension in drawing spec H H H H H H H H H H H H H	f≤1/3w, h ≤1/3H, dimension in drawing spec-> OK Conducive material and ITO/PDA connective area must over than 1/2. Entire dimension must be in spec tolerance.		$\checkmark$
8.6.6.3	FPC appearance	Hot pressing material get broken, folding line open; FPC golden finger oxidate, broken ,scratch ,foreign material which cause line short	Broken length<2mm; FPC line is OK- > Accepted Crack and line broken->Rejected		$\checkmark$
8.6.6.4	FPC burr	Burr near FPC edge area	When cover line and burr length ≤1.0mm->Accepted		$\checkmark$

8.6.6.5	FPC falling off	FPC bonding area falling off ; silica gel breaking	Rejected		$\checkmark$
8.6.6.6	Sealant missing ITO line	Sealant is not covered all ITO line	Rejected	$\checkmark$	
8.6.6.7	Missing sealant	No sealant	Rejected	$\checkmark$	
8.6.6.8	Sealant	Sealant height ->product total height	Rejected	$\checkmark$	

### 8.6.7 SMT

No.	Item	Description	Accepted criterion	MA.	MI.
8.6.7.1	Soldering bridge	Solder between adjacent pads and components	Rejected		$\checkmark$
8.6.7.2	Solder ball/splash	Solder ball/tin dross causing short circuit at the solder point. There are active solder ball and splash.	Rejected		$\checkmark$
8.6.7.3	Soldering excursion	Soldering slant > 1/3 soldering pad	Rejected		$\checkmark$
8.6.7.4	Component wrong attaching	Component on PCB differs with drawing: wrong one, extra one,lack one,opposite polarity	Rejected	V	
		JUMP short circuit on PCB: extra soldering ,lack soldering.	Rejected	$\checkmark$	
8.6.7.5	Component falling off	Soldering but component is missing	Rejected	$\checkmark$	
8.6.7.6	Wrong component	Component model/spec differs from product specification	Rejected	$\checkmark$	

8.6.8 General Appearance

No.	ltem	Description	Accepted criterion	MA.	MI.
8.6.8.1	Dimension	According to drawing	Accepted	$\checkmark$	
8.6.8.2	Surface stain	Defect mark or label are not removed residual glue, and finger print,etc;	Rejected		$\checkmark$
8.6.8.3	Assembly foreign material	Dot/linear stain after assembly backlight and diffuse film TP assembly fogy stain	Invisible when power on->OK Refer to 6.2.2 dot/line spec		$\checkmark$
8.6.8.4	Mixture	Different model product in the same shipment	Rejected	$\checkmark$	
8.6.8.5	Product mark	Missing, unclear, incorrect, or misplaced part	Rejected		$\checkmark$

8.6.8.6	Componen t mark	Silk screen mark clear, resistance measured value in spec	Accepted (Refer to customer special requirement)	$\checkmark$
8.6.8.7	Newton's rings	Area<1/6 screen area quantity≤1	Accepted	$\checkmark$
8.6.8.8	Mura	1.In black display ND 3% invisible ->OK; visible->NG 2.Naked eyes inspection RGB display invisible Black display, area<1/4 screen area	Refer to limited sample	V
8.6.8.9	Light leak	1.LCD edge(near backlight) shadow by LCD lamps irregular illuminate 2.Judge in black/white/gray display (slight leaky is yellowish,greenish, blueish ->NG); Tape 洋地 滿 光	Refer to limited sample	V
8.6.8.10	Polarizer	<ul><li>1.Polarizer slant.Cover VA and not over</li><li>LCD edge</li><li>2.No unmovable stain or finger print in polarizer VA</li><li>3.Bubble/warped but not enter VA</li></ul>	Accepted	V
8.6.8.11	TP defect	1.TP crack 2.TP stain(fogy& unremovable) 3.TP glue overflow to VA	Rejected	$\checkmark$

#### Remark :

Anything which is not clearly defined in  $6.5 \sim 6.8$  should refer to IPC-A-610E.Consumer Electronics, Non-consumer Electronics refer to I grade and Industrial, Automobile refer to II grade.

#### 8.7 Others

Items not specified in this document or released on compromise should be inspected with reference to mutual agreement and limit samples.

## 9. HANDLING PRECAUTIONS

#### 9.1 Mounting method

The LCD module consists of two thin glass plates with polarizes which easily be damaged. And since the module in so constructed as to be fixed by utilizing fitting holes in the printed circuit board.

Extreme care should be needed when handling the LCD modules.

#### 9.2 Caution of LCD handling and cleaning

When cleaning the display surface, Use soft cloth with solvent

[recommended below] and wipe lightly :

- •.lsopropyl alcohol
- Ethyl alcohol

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

- Do not use the following solvent :
- Water
- Aromatics

Do not wipe ITO pad area with the dry or hard materials that will damage the ITO patterns

Do not use the following solvent on the pad or prevent it from being contaminated :

- Soldering flux
- •.Chlorine (Cl) , Sulfur (S)

If goods were sent without being silicon coated on the pad, ITO patterns could be damaged due to the corrosion as time goes on.

If ITO corrosion happen by miss-handling or using some materials such as Chlorine (CI), Sulfur (S) from customer, Responsibility is on customer.

#### 9.3 Caution against static charge

The LCD module use C-MOS LSI drivers, so we recommended that you :

Connect any unused input terminal to Vdd or Vss, do not input any signals before power is turned on, and ground your body, work/assembly areas, assembly equipment to protect against static electricity.

#### 9.4 Packing

Module employ LCD elements and must be treated as such.

• Avoid intense shock and falls from a height.

•. To prevent modules from degradation, do not operate or store them exposed direct to sunshine or high temperature/humidity.

#### 9.5 Caution for operation

•. It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life.

•. An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.

•.Response time will be extremely delayed at lower temperature then the operating temperature range and on the other hand at higher temperature LCD's how dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operation temperature.

•. If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.

- •.A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.
- •.Usage under the maximum operating temperature, 50%Rh or less is required.
- •.When fixed patterns are displayed for a long time, remnant image is likely to occur.

#### 9.6 Storage

In the case of storing for a long period of time for instance, for years for the purpose or replacement use, the following ways are recommended.

•. Storing in an ambient temperature 10°C to 30°C, and in a relative humidity of 45% to 75%. Don't expose to sunlight or fluorescent light.

- •.Storing in a polyethylene bag with the opening sealed so as not to enter fresh air outside in it . And with no desiccant.
- •.Placing in a dark place where neither exposure to direct sunlight nor light's keeping the storage temperature range.
- •.Storing with no touch on polarizer surface by the anything else.

It is recommended to store them as they have been contained in the inner container at the time of delivery from us.

#### 9.7 Safety

•. It is recommendable to crash damaged or unnecessary LCD's into pieces and wash off liquid crystal by either of solvents such as acetone and ethanol, which should be burned up later.

•.When any liquid leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

## **10. PRECAUTION FOR USE**

**10.1** A limit sample should be provided by the both parties on an occasion when the both parties agreed its necessity. Judgment by a limit sample shall take effect after the limit sample has been established and confirmed by the both parties.

**10.2** On the following occasions, the handing of problem should be decided through discussion and agreement between responsible of the both parties.

•.When a question is arisen in this specification.

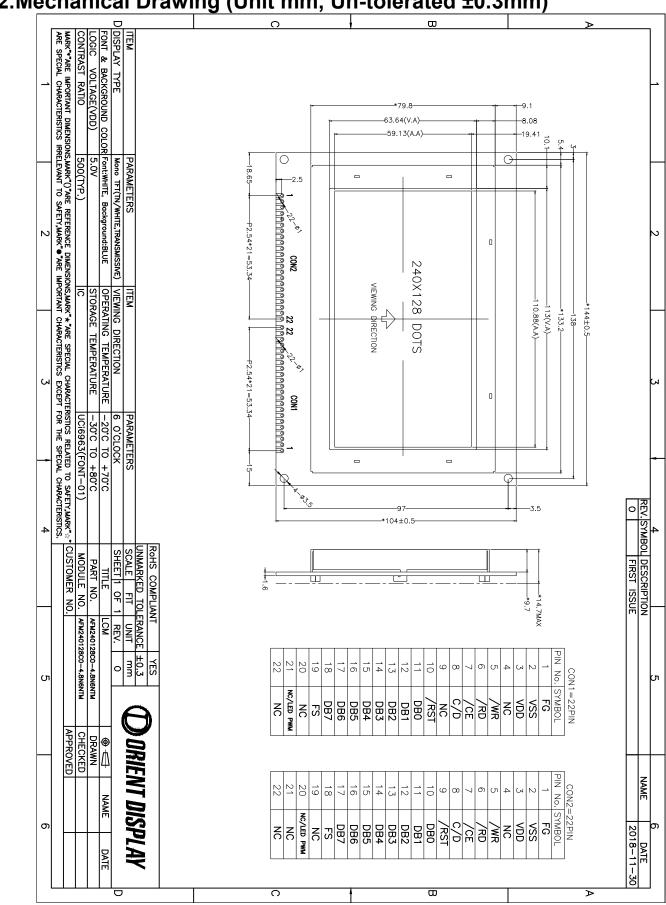
•.When a new problem is arisen which is not specified in this specifications.

•.When an inspection specifications change or operating condition change in customer is reported to ODNA, and some problem is arisen in this specification due to the change.

•.When a new problem is arisen at the customer's operating set for sample evaluation in the customer site.

#### **11. PACKING SPECIFICATION**

---TBD



## 12.Mechanical Drawing (Unit mm, Un-tolerated ±0.3mm)